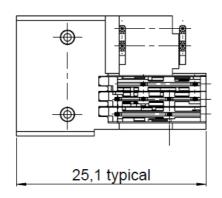
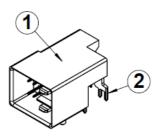


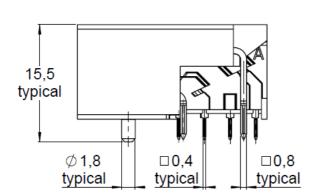


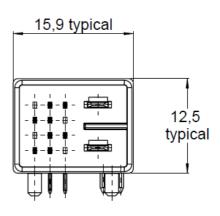
OCTIS COMBO BOARD CONNECTOR 10 POS PIP

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All dimensions are in mm. Tolerances according ISO 2768 m-H

## **DESCRIPTION**

REP	COMPONENT	MATERIALS	PLATING
1	Housing	PLASTIC	-
2	Contact	COPPER ALLOY	SN



# **Technical Data Sheet**

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## **GENERAL CHARACTERISTICS**

Mechanical  Mating endurance (cycles)  Vibration  Weight (g)	IEC 61300-2-2 EIA 364-28 -	100 - 2.0900
Environmental Operating temperature (°C) Storage temperature (°C) RoHS Flammability	IEC 61300-2-22 IEC 61300-2-22 - UL 94	-40 / +85 -65 / +85 Compliant V0
Electrical		
Signal pins Working voltage (V AC Max) Contact resistance (mΩ max) Current rating (A) Insulation resistance (MΩ min)	- EIA 364-23B EIA 364-70A EIA 364-21C	300 55 1 A per contact (all contacts powered) 5000 (after environmental exposure)
Signal Integrity performance Cross talk Impedance of pairs	-	Max. 300V AC (r.m.s.) 16A in combination with 1.5mm2 conductors (16AWG) 20A in combination with 2.5mm2 (14AWG) & 3.3mm2 conductors (12AWG)
IL RL	EIA 364-20 EIA 364-21	500V AĆ 5000MΩ minimum initial
Power pins Working voltage Current rating Dielectric withstand voltage Insulation Resistance	- - EIA 364-20 EIA 364-21	1000MΩ minimum after environmental aging  Max. 300 AC or DC  16A with AWG16 wire (7xAWG24)  20A with AWG14 wire (7xAWG22)  5000MΩ minimum initial  1000MΩ minimum after environmental aging
Others Packaging	-	Packaging in Tape&Reel (Quantity per reel to be defined)

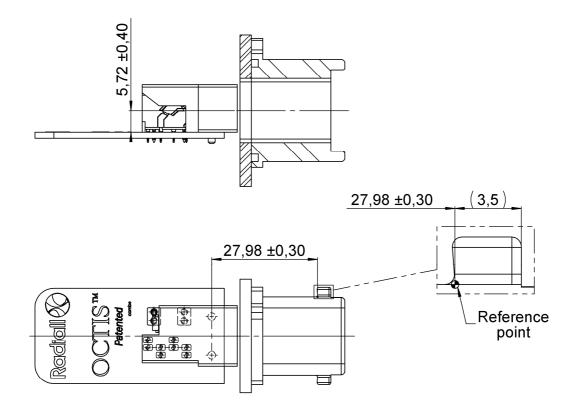


# **Technical Data Sheet**

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## **POSITIONING AND PATTERN DEFINITION**







OCTIS COMBO BOARD CONNECTOR 10 POS PIP

PAGE 4/6 ISSUE 13-02-19A SERIES OCTIS PART NUMBER OCTI560500 FOOT/PRINT (General tolerance for PCB ±0.1 mm) Receptacle central axis Radial 1,6~2.4 (±10%) (PCB Thickness) Patented Keep out zone 0.1 65 All holes  $\oplus \oplus$ 65 6 (x2)6(2x4)2.3 (x2)±0,30 R<sub>0.3</sub> 5,1 Ø2 ±0,05  $(x4) Ø 1,3 \pm 0,05$ 10,2 (Metalized) 3,85 17,9 (X2) (x4) Ø 1,76(Land) DETAIL C Solder mask-(8x4) R0,3 (x8) 1,5 5,075 3,95 2 2  $(x8) Ø 0,75 \pm 0,05$ (Metalized) x8) 4,45 3,4 (x8) Ø 1,2(Land)  $\bigcirc$ 4 က်  $\infty$ 3,4 Solder 9 mask 0, Receptacle **DETAIL A** central axis **DETAIL B** 

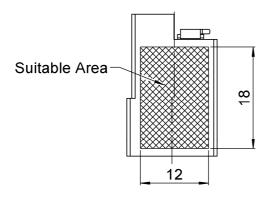


# **Technical Data Sheet**

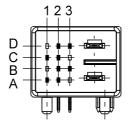
OCTIS COMBO BOARD CONNECTOR 10 POS PIP

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#### SUITABLE AREA FOR PICK & PLACE VACUUM NOZZLE



# **CONTACTS CONFIGURATION**







OCTIS COMBO BOARD CONNECTOR 10 POS PIP

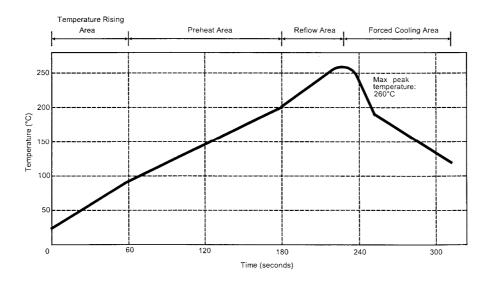
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#### **SOLDER PROCEDURE\***

- Deposit solder paste (Sn Ag4 Cu0.5) on solder pads / mounting area by screen printing application. We recommend a low residue flux. Verify that the edges of the pads are clean.
- Place the component on the mounting area with a pick & place machine.
   A video camera is recommended for a good positioning of the component.
   Adhesive agents must not be used on the component.
- This process of soldering has been tested with a convection oven.
   Below please find the typical soldering profile to use.
- 4. Optional cleaning of printed circuit board.
- 5. Check solder joints and position of the component by visual inspection.

Note: When soldering a receptacle, no plug should be mated to the receptacle before completion of this procedure.

## **TEMPERATURE PROFILE**



Parameter	Value	Unit
Temperature rising Area	1 to 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

<sup>\*</sup> Typical data for reflow process. Alternatively, wave soldering is also possible

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